

MM54HC00/MM74HC00 Quad 2-Input NAND Gate

General Description

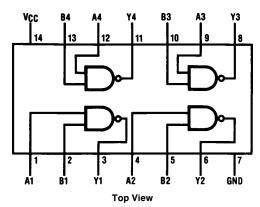
These NAND gates utilize advanced silicon-gate CMOS technology to achieve operating speeds similar to LS-TTL gates with the low power consumption of standard CMOS integrated circuits. All gates have buffered outputs. All devices have high noise immunity and the ability to drive 10 LS-TTL loads. The 54HC/74HC logic family is functionally as well as pin-out compatible with the standard 54LS/74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to $V_{\rm CC}$ and ground.

Features

- Typical propagation delay: 8 ns
- Wide power supply range: 2-6V
- Low quiescent current: 20 µA maximum (74HC Series)
- Low input current: 1 μA maximum
- Fanout of 10 LS-TTL loads

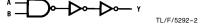
Connection and Logic Diagrams

Dual-In-Line Package



TL/F/5292-1

Order Number MM54HC00 or MM74HC00



Absolute Maximum Ratings (Notes 1 & 2)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Supply Voltage (V _{CC})	-0.5 to $+7.0$ V
DC Input Voltage (V _{IN})	-1.5 to $V_{\rm CC} + 1.5 V_{\rm CC}$
DC Output Voltage (V _{OUT})	-0.5 to $V_{\rm CC} + 0.5 V_{\rm CC}$
Clamp Diode Current (I _{IK} , I _{OK})	\pm 20 mA
DC Output Current, per pin (I _{OUT})	\pm 25 mA
DC V _{CC} or GND Current, per pin (I _{CC})	\pm 50 mA
Storage Temperature Range (T _{STG})	-65°C to +150°C
Dawer Dissination (D.)	

Power Dissipation (P_D)

(Note 3) 600 mW S.O. Package only 500 mW

Lead Temperature (T_L)

(Soldering 10 seconds)

Supply Voltage (V_{CC}) 2 6 DC Input or Output Voltage 0 V_{CC}

Max

+85

+125

Units

V

٧

°C

ns

ns

ns

(V_{IN}, V_{OUT})
Operating Temp. Range (T_A)
MM74HC

Operating Conditions

MM54HC Input Rise or Fall Times (t_r, t_f) $V_{CC} = 2V$

 $\begin{array}{lll} V_{CC}\!=\!2V & 1000 \\ V_{CC}\!=\!4.5V & 500 \\ V_{CC}\!=\!6.0V & 400 \end{array}$

-40

-55

DC Electrical Characteristics (Note 4)

Symbol	Parameter	Conditions	v _{cc}	T _A = 25°C		74HC T _A = -40 to 85°C	54HC T _A = -55 to 125°C	Units	
				Typ Guaranteed Limits					
V_{IH}	Minimum High Level Input Voltage		2.0V 4.5V 6.0V		1.5 3.15 4.2	1.5 3.15 4.2	1.5 3.15 4.2	V V V	
V _{IL}	Maximum Low Level Input Voltage**		2.0V 4.5V 6.0V		0.5 1.35 1.8	0.5 1.35 1.8	0.5 1.35 1.8	V V V	
V _{OH}	Minimum High Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $ I_{OUT} \le 20 \mu A$	2.0V 4.5V 6.0V	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V V V	
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $ I_{OUT} \le 4.0 \text{ mA}$ $ I_{OUT} \le 5.2 \text{ mA}$	4.5V 6.0V	4.2 5.7	3.98 5.48	3.84 5.34	3.7 5.2	V V	
V _{OL}	Maximum Low Level Output Voltage	$V_{IN} = V_{IH}$ $ I_{OUT} \le 20 \mu A$	2.0V 4.5V 6.0V	0 0 0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V V V	
		$V_{IN} = V_{IH}$ $ I_{OUT} \le 4.0 \text{ mA}$ $ I_{OUT} \le 5.2 \text{ mA}$	4.5V 6.0V	0.2 0.2	0.26 0.26	0.33 0.33	0.4 0.4	V V	
I _{IN}	Maximum Input Current	V _{IN} =V _{CC} or GND	6.0V		±0.1	±1.0	±1.0	μΑ	
Icc	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND $I_{OUT} = 0 \mu A$	6.0V		2.0	20	40	μΑ	

260°C

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

 $[\]textbf{Note 3:} \ \ Power \ Dissipation \ temperature \ derating \\ -- plastic "N" \ package: \\ -- 12 \ mW/^{o}C \ from \ 65^{o}C \ to \ 85^{o}C; \ ceramic "J" \ package: \\ -- 12 \ mW/^{o}C \ from \ 100^{o}C \ to \ 125^{o}C.$

Note 4: For a power supply of 5V $\pm 10\%$ the worst case output voltages (V_{CH}, and V_{CL}) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at V_{CC}=5.5V and 4.5V respectively. (The V_{IH} value at 5.5V is 3.85V.) The worst case leakage current (I_{IN}, I_{CC}, and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0V values should be used.

^{**} V_{IL} limits are currently tested at 20% of V_{CC} . The above V_{IL} specification (30% of V_{CC}) will be implemented no later than Q1, CY'89.

AC Electrical Characteristics $v_{CC}\!=\!5\text{V},\,T_{A}\!=\!25^{\circ}\text{C},\,C_{L}\!=\!15\,\text{pF},\,t_{r}\!=\!t_{f}\!=\!6\,\text{ns}$

Symbol	Parameter	Conditions	Тур	Guaranteed Limit	Units
t _{PHL} , t _{PLH}	Maximum Propagation Delay		8	15	ns

$\textbf{AC Electrical Characteristics} \ \ V_{CC} = 2.0 \ \ \text{to 6.0V}, \ C_L = 50 \ \ \text{pF}, \ t_f = t_f = 6 \ \text{ns (unless otherwise specified)}$

Symbol	Parameter	Conditions	v _{cc}	T _A = 25°C		74HC T _A = -40 to 85°C	54HC T _A = -55 to 125°C	Units
				Тур	Guaranteed Limits			
t _{PHL} , t _{PLH}	Maximum Propagation Delay		2.0V 4.5V 6.0V	45 9 8	90 18 15	113 23 19	134 27 23	ns ns ns
t _{TLH} , t _{THL}	Maximum Output Rise and Fall Time		2.0V 4.5V 6.0V	30 8 7	75 15 13	95 19 16	110 22 19	ns ns ns
C _{PD}	Power Dissipation Capacitance (Note 5)	(per gate)		20				pF
C _{IN}	Maximum Input Capacitance			5	10	10	10	pF

 $\textbf{Note 5:} \ \ C_{PD} \ \ \text{determines the no load dynamic power consumption, } P_D = C_{PD} \ V_{CC}^2 \ f + I_{CC} \ V_{CC}, \ \text{and the no load dynamic current consumption, } I_S = C_{PD} \ V_{CC} \ f + I_{CC} \ V_{CC}, \ \text{and the no load dynamic current consumption, } I_S = C_{PD} \ V_{CC} \ f + I_{CC} \ V_{CC}, \ \text{and the no load dynamic current consumption, } I_S = C_{PD} \ V_{CC} \ f + I_{CC} \ V_{CC}, \ \text{and the no load dynamic current consumption, } I_S = C_{PD} \ V_{CC} \ f + I_{CC} \ V_{CC}, \ \text{and the no load dynamic current consumption, } I_S = C_{PD} \ V_{CC} \ f + I_{CC} \ V_{CC}, \ \text{and the no load dynamic current consumption, } I_S = C_{PD} \ V_{CC} \ f + I_{CC} \ V_{CC}, \ \text{and the no load dynamic current consumption, } I_S = C_{PD} \ V_{CC} \ f + I_{CC} \ V_{CC}, \ \text{and the no load dynamic current consumption, } I_S = C_{PD} \ V_{CC} \ f + I_{CC} \ V_{CC}, \ \text{and the no load dynamic current consumption, } I_S = C_{PD} \ V_{CC} \ f + I_{CC} \ V_{CC}, \ \text{and the no load dynamic current consumption, } I_S = C_{PD} \ V_{CC} \ f + I_{CC} \ V_{CC}, \ \text{and the no load dynamic current consumption, } I_S = C_{PD} \ V_{CC} \ f + I_{CC} \ V_{CC}, \ \text{and the no load dynamic current consumption, } I_S = C_{PD} \ V_{CC} \ f + I_{CC} \ V_{CC}, \ \text{and the no load dynamic current consumption, } I_S = C_{PD} \ V_{CC} \ f + I_{CC} \ V_{CC}, \ \text{and the no load dynamic current consumption, } I_S = C_{PD} \ V_{CC} \ f + I_{CC} \ V_{CC}, \ \text{and the no load dynamic current consumption, } I_S = C_{PD} \ V_{CC} \ f + I_{CC} \ V_{CC}, \ \text{and the no load dynamic current consumption, } I_S = C_{PD} \ V_{CC} \ f + I_{CC} \ V_{CC} \ f + I_{CC} \ V_{CC}, \ \text{and the no load dynamic current consumption, } I_S = C_{PD} \ V_{CC} \ f + I_{CC} \ V_{CC} \ f + I_{CC} \ V_{CC}, \ \text{and the no load dynamic current consumption, } I_S = C_{PD} \ V_{CC} \ f + I_{CC} \$

Physical Dimensions inches (millimeters) (19.939) MAX 14 [3] [2] [1] [10] [9] [8] 0.025 (0.635)0.220-D.310 RAD (5.588-7.874) 1 2 3 4 5 6 7 0.290-0.320 0.200 (5.080) MAX 0.020-0.060 (D.127) MIN (7.366-8.128) 0.060 ± 0.005 (1.524 ±0.127) 0.180 (0.508-1.524) -MA (4.572) 95° ±5 86°94° TYF 10° MAX 0.008-0.012

(0.203-D.305)

MAX BOTH ENDS

0.098

(2.489)

0.310-0.410

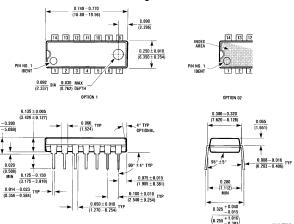
(7.874-10.41)

Cavity Dual-In Line Package (J) Order Number MM54HC00J or MM74HC00J NS Package J14A

(0.457 ±0.076)

0.100 ±0.010

(2 540 +0 254)



Molded Dual-In Line Package (N) Order Number MM74HC00N NS Package N14A

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0.125-0.200

(3.175-5.080)

J14A (REV G)

(3.81) MIN



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